



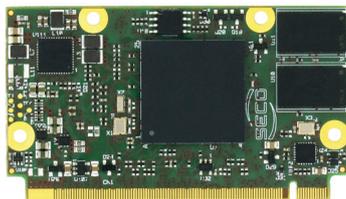
μQ7-A75-J

μQseven® standard module with NXP i.MX6 Processor

Small, flexible OTS module at proprietary costs



"Ready-to-use" and "ready-to-market" cost-effective product which exclusively supports SoC native features



HIGHLIGHTS

- Excellent price-performance ratio
- The best combination of low power consumption, size and price
- Complete BSP, easy migration between the entire i.MX6 product family



MAIN FIELDS OF APPLICATION



HMI



Internet of Things



PDA Electronics



Wireless Technologies

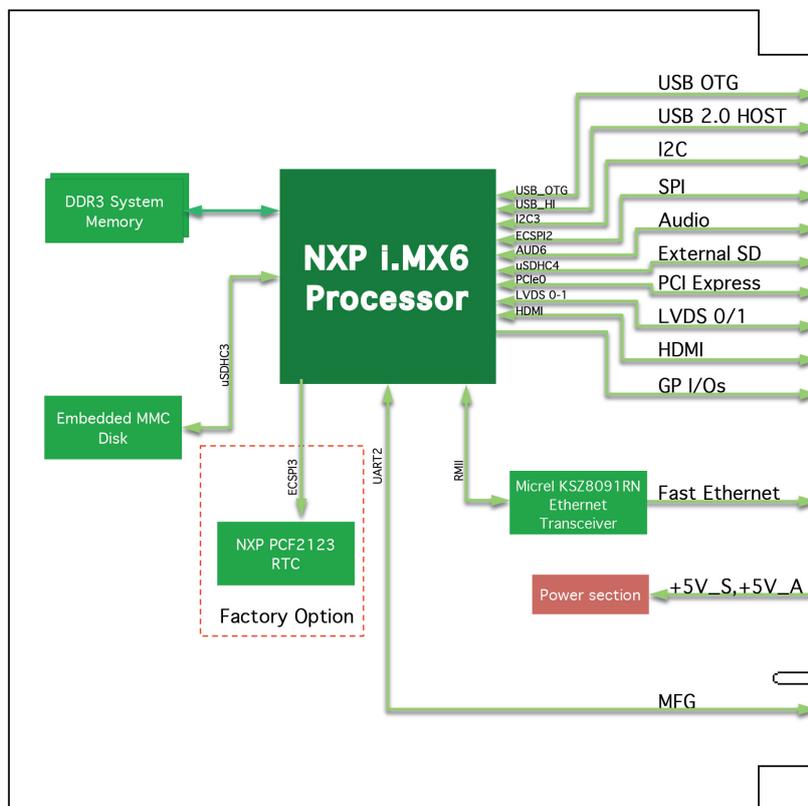
FEATURES

Processor	NXP i.MX6 Family, based on ARM® CORTEX-A9 processors - i.MX6S Solo - Single core up to 1GHz - i.MX6DL Dual Lite - Dual core up to 1GHz per core	Other Interfaces	On the card edge connector, many pins can be used as General Purpose I / Os or to implement some(*) of the following extra functionalities: - Additional SD interface - Up to 4 UARTs - CAN interface - Watchdog(s) - I2C interfaces - PWM outputs - SPI interface - Additional Audio interface (*) not all the combinations are allowed simultaneously Power Management Signals
Max Cores	2		
Memory	Up to 1GB DDR3L on-board (up to 512MB with i.MX6S Solo)	Power Supply	+5V _{DC} ± 5% Optional Low Power RTC
Graphics	Dedicated 2D Hardware accelerator Dedicated 3D Hardware accelerator, supports OpenGL® ES2.0 3D Supports 2 independent displays		
Video Interfaces	1 x LVDS Dual Channel or 2 x LVDS Single Channel 18 / 24 bit interface HDMI Interface	Operating System	Linux Yocto
Video Resolution	LVDS, resolution up to 1920x1200 HDMI, resolution up to 1080p		
Mass Storage	On-board eMMC drive, up to 8 GB SD / MMC / SDIO interface Internal SPI Flash for booting	Operating Temperature*	0°C ÷ +60 °C (Commercial temp.) For Industrial temp. (-40°C ÷ +85°C) please contact us
Networking	FastEthernet (10 / 100 Mbps) interface		
USB	1 x USB OTG interface 1 x USB 2.0 Host interface	Dimensions	40 x 70 mm (1.57" x 2.76")
PCI-e	1 x PCI-e x1 lane (only PCI-e 1.1 and Gen2 are supported)		
Audio	I2S / AC'97 Audio interface	*Measured at any point of the heatspreader/heatsink during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.	

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BLOCK DIAGRAM



ORDERING INFORMATION

PN*	DESCRIPTION
QA75-1110-1000-C0	μQ7 w / i.MX6 Solo - RAM DDR3L 256MB single chip - eMMC 4GB - RTC Low Power - Comm.Temp
QA75-2310-1000-C0	μQ7 w / i.MX6 DualLite - RAM DDR3L 512MB dual chip - eMMC 4GB - RTC Low Power - Comm.Temp
QA75-2410-1000-C0	μQ7 w / i.MX6 DualLite - RAM DDR3L 1GB dual chip - eMMC 4GB - RTC Low Power - Comm.Temp

*Additional configurations may be available. Please inquire for more information.

ACCESSORIES

PN	DESCRIPTION
QA42-0000-2111-I0	Carrier Board for Qseven® rel. 2.0 Compliant modules on 3.5" Form factor - HDMI - 2nd Ethernet Port - LVDS - Debug Port
QA30-Q7XDK-0000	Qseven® Cross Platform Development Kit 2.0
QA42-Q7XSK-2100	Q7 - Cross Platform Starter Kit 2.0 - HDMI - LVDS, 7" touch display included
QA75-DISS-1-PK	μQ7 w / i.MX6 Solo & Dual Heat Spreader (PASSIVE)
QA75-DISS-2-PK	μQ7 w / i.MX6 Solo & Dual Heat Sink (PASSIVE)
ASK-425	Adapter for mounting a microQ7 module on standard Qseven® carrier boards